

## **AMENDMENTS TO THE CLAIMS**

Please amend the claims as follows:

### **Listing of Claims:**

Claims 1-21 (Cancelled).

Claim 22 (Currently Amended): An A single monolithic electronic device having an upper side and a lower side that is arranged opposite of the upper side, the device comprising:  
an integrated circuit chip configured to include informative data having security-  
sensitive content, wherein

the upper-a first side of the chip-device includes comprising at least one first conductive element connected to the integrated circuit, and  
the lower-a second side of the chip-device includes comprising at least one second conductive element, ~~the second side being opposite of the first side,~~ the first conductive element and the second conductive element being coupled by inductive coupling, the second conductive element not being electrically connected to the integrated circuit chip and the first conductive element.

Claim 23 (Cancelled).

Claim 24 (Previously Presented): A device according to claim 22, wherein the first conductive element and the second conductive element include alternate intermingled, wound, or intertwined patterns.

Clam 25 (Previously Presented): A device according to claim 22, wherein the first conductive element includes a transmitting armature.

Claim 26 (Previously Presented): A device according to claim 22, wherein the first conductive element and/or the second conductive element include an inductance.

Claim 27 (Previously Presented): A device according to claim 22, wherein the second conductive element includes a ground plane conductance or a low resistance.

Claim 28 (Previously Presented): A device according to claim 22, further comprising an electromagnetic excitation device for electromagnetic excitation of the first conductive element.

Claim 29 (Currently Amended): A device according to claim 22, further comprising:  
~~an inductance measuring device in connection with the first conductive element for measuring an inductance of at least one of the conductive elements of the first conductive element, and and/or for detecting a variation in of the inductance.~~

Claim 30 (Currently Amended): A device according to claim 29, further comprising:  
~~a deletion unit means for deleting or ceasing to store data of the measured inductance in the integrated circuit chip, in an event of if a change of the inductance is being detected in a value of the inductance by the inductance measuring device.~~

Claim 31 (Previously Presented): A device according to claim 22, wherein the first conductive element is connected to the integrated electronic circuit inside the chip, whereas the second conductive element is not connected to the integrated circuit chip and the first conductive element.

Claim 32 (Previously Presented): A device according to claim 22, wherein the integrated circuit chip includes upper coating layers including at least one metal or conductive level allowing the first conductive element to be connected with the integrated electronic circuit.

Claim 33 (Previously Presented): A device according to claim 22, wherein the first conductive element forms a circuit loop.

Claim 34 (Previously Presented): A device according to claim 22, wherein the second conductive element forms an earth plane or an equipotential.

Claim 35 (Previously Presented): A device according to claim 22, wherein the first conductive element includes at least one longilinear metal track.

Claim 36 (Previously Presented): A device according to claim 22, wherein the first conductive element includes plural interconnected sections arranged in a substantially concentric way, so as to form a corrugation or a polygonal spiral or to form a substantially circular spiral.

Claim 37 (Previously Presented): A device according to claim 22, wherein the first conductive element includes plural interconnected sections arranged in a substantially parallel way so as to form at least one meander or one coil.

Claim 38 (Previously Presented): A device according to claim 22, wherein the second conductive element includes a plane or a metal plated surface portion or a network of

conductive meshes, or a network of substantially circular, square, hexagonal or polygonal meshes, or a grid.

Claim 39 (Previously Presented): A device according to claim 22, wherein each conductive element lies in a plane substantially parallel to a side surface of the integrated circuit chip.

Claim 40 (Previously Presented): A device according to claim 22, wherein the conductive elements of the integrated circuit chip are coated with an encapsulation material.

Claim 41 (Previously Presented): A chip card, including at least one electronic device according to claim 22.

Claim 42 (Previously Presented): An encryption or decoding device including one or more electronic devices according to claim 22.

Claim 43 (New): A device according to claim 22, wherein the integrated circuit chip is arranged between the upper side and the lower side of the device.